



METHOD OF FORMING A MULTI-LAYER SEMICONDUCTOR STRUCTURE INCORPORATING A PROCESSING HANDLE MEMBER

Rafael Reif, et al.
Application No. 10/749,103

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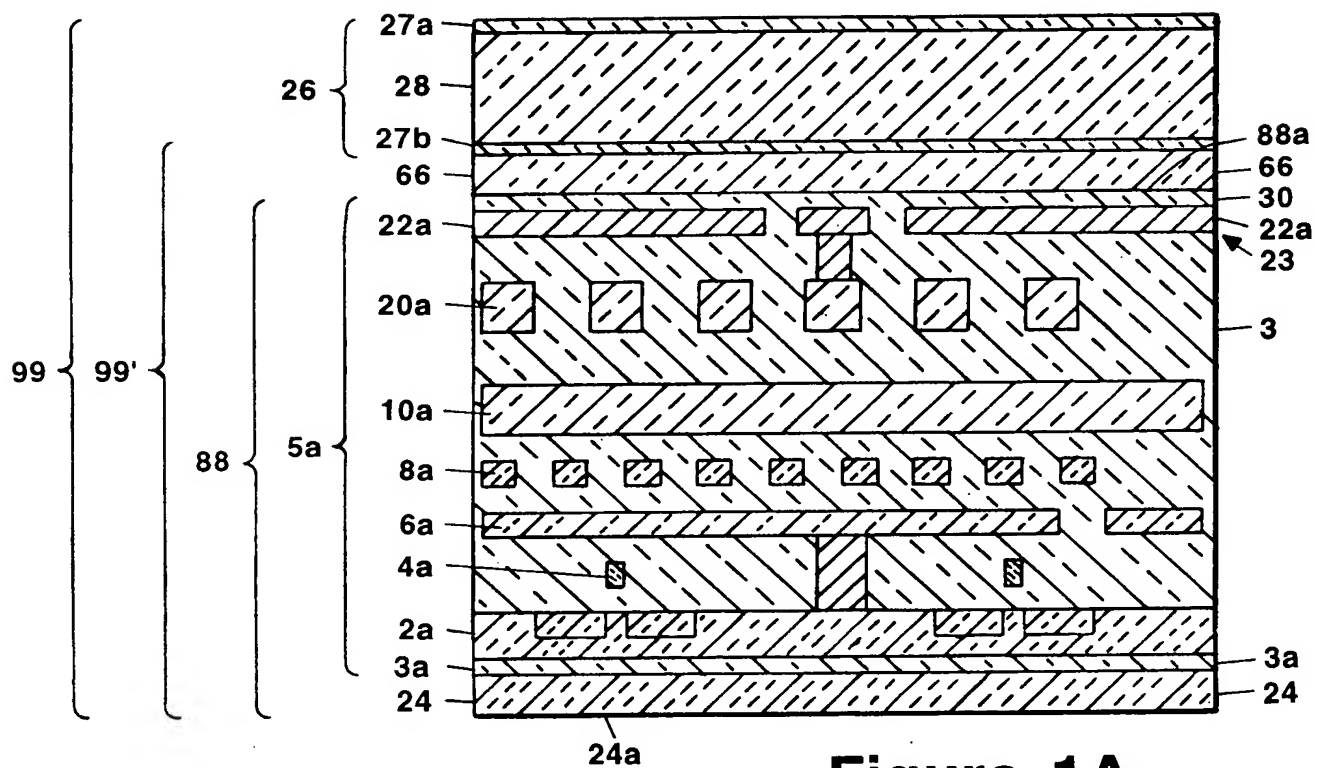


Figure 1A

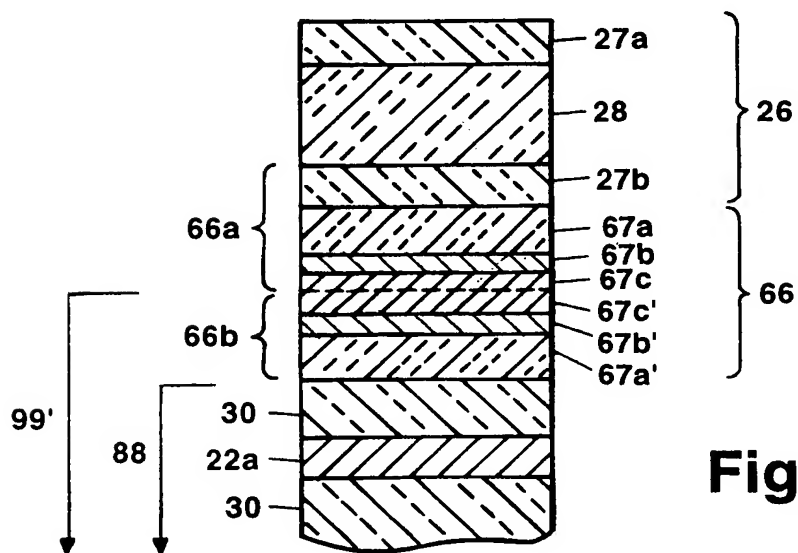


Figure 1B



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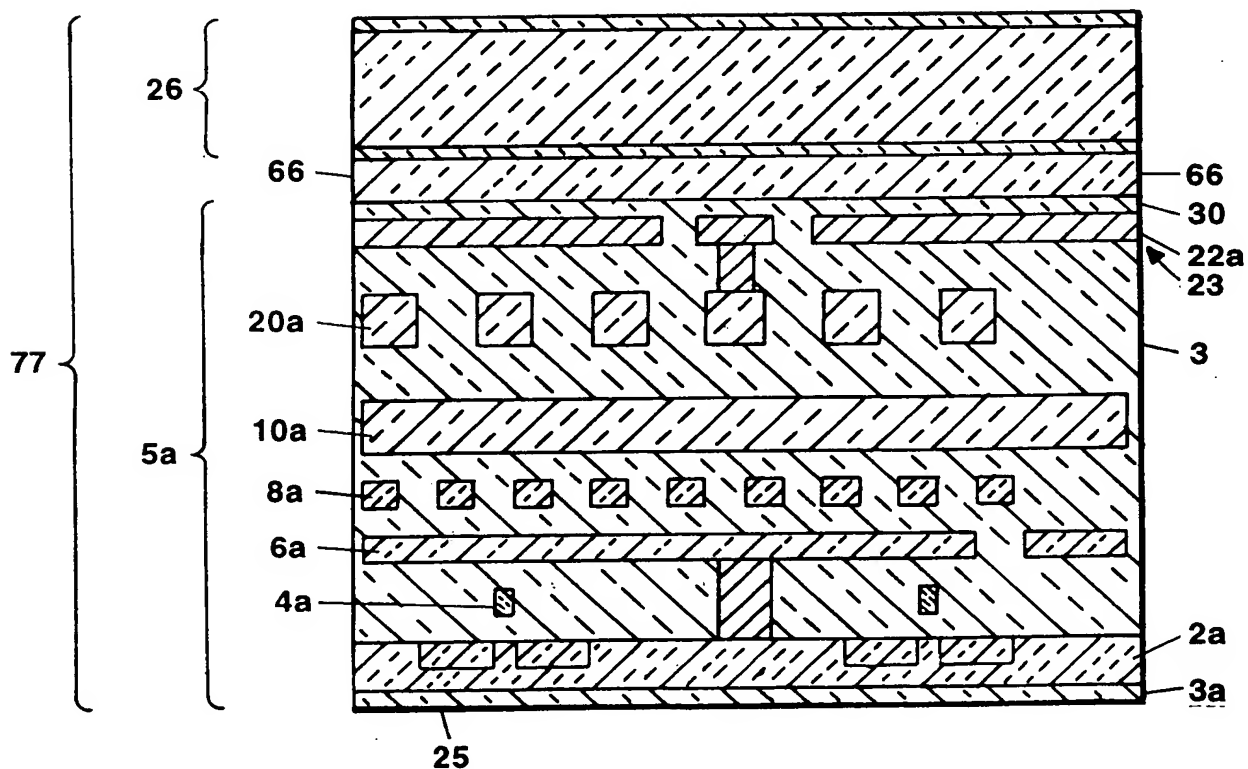


Figure 2A



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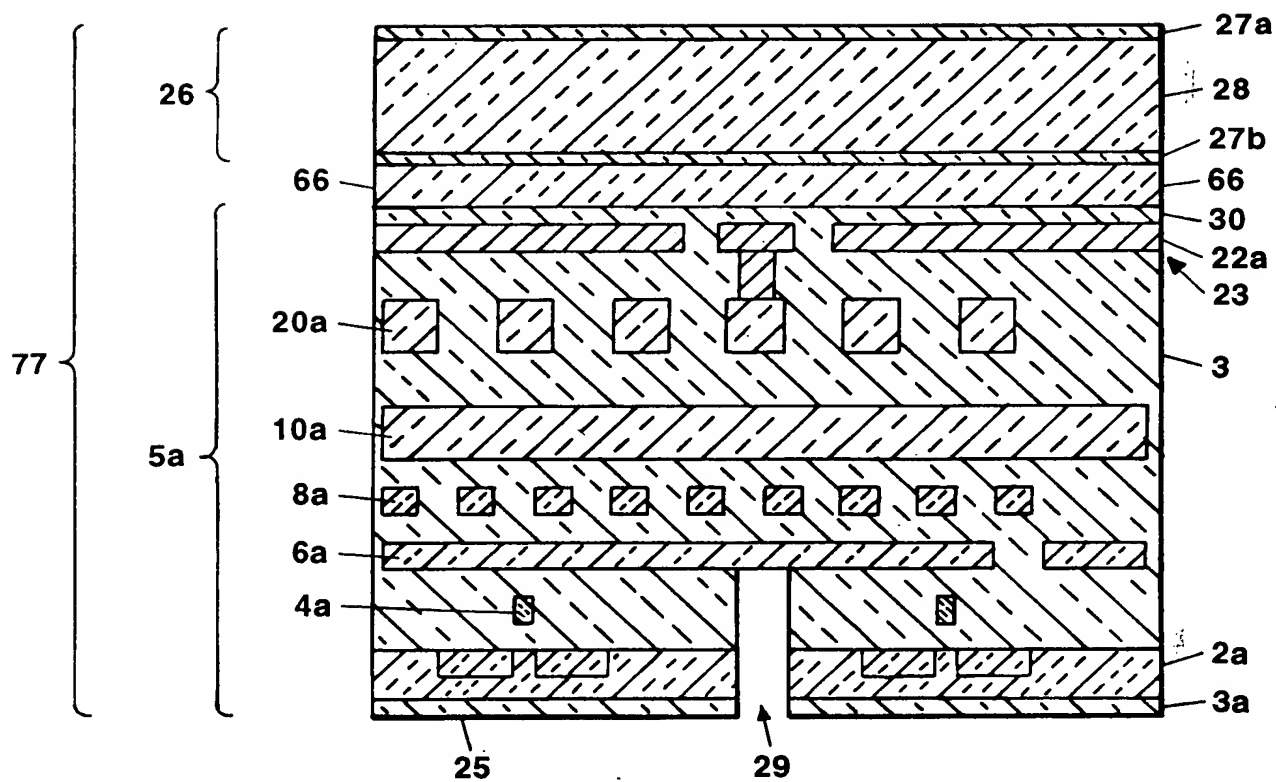


Figure 2B



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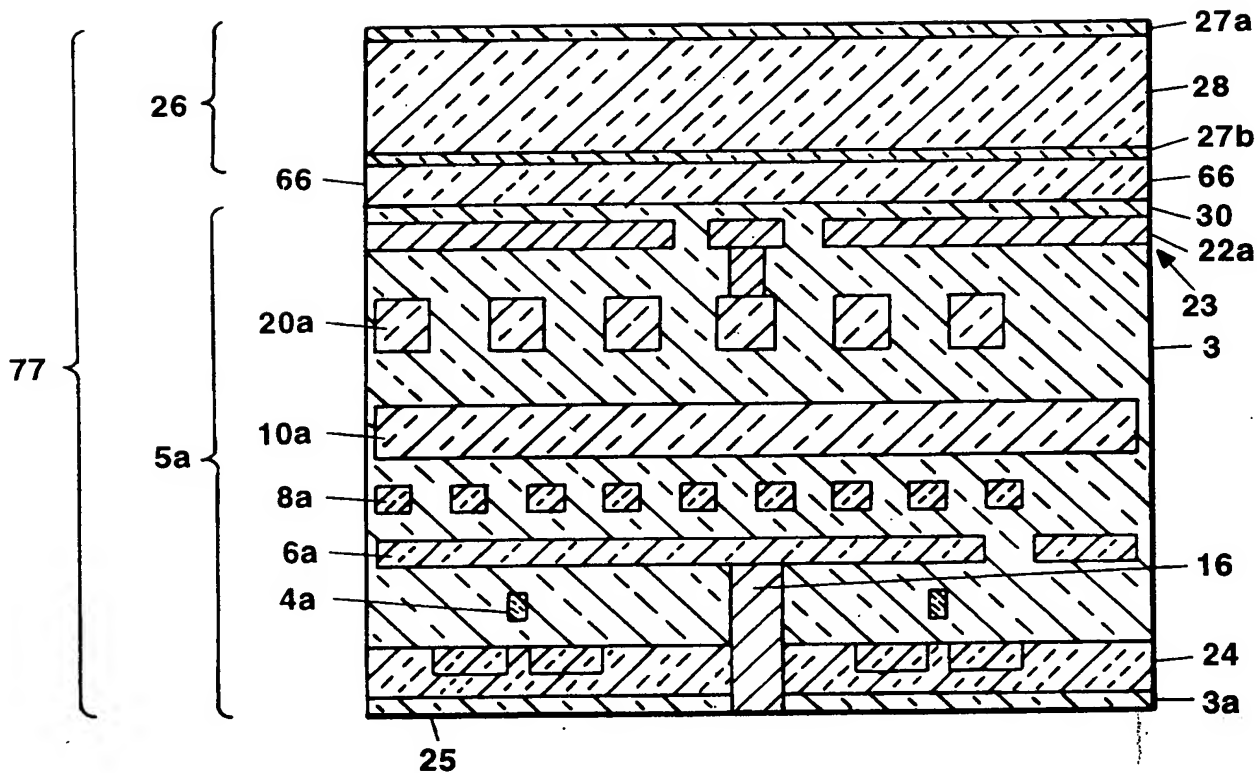


Figure 2C



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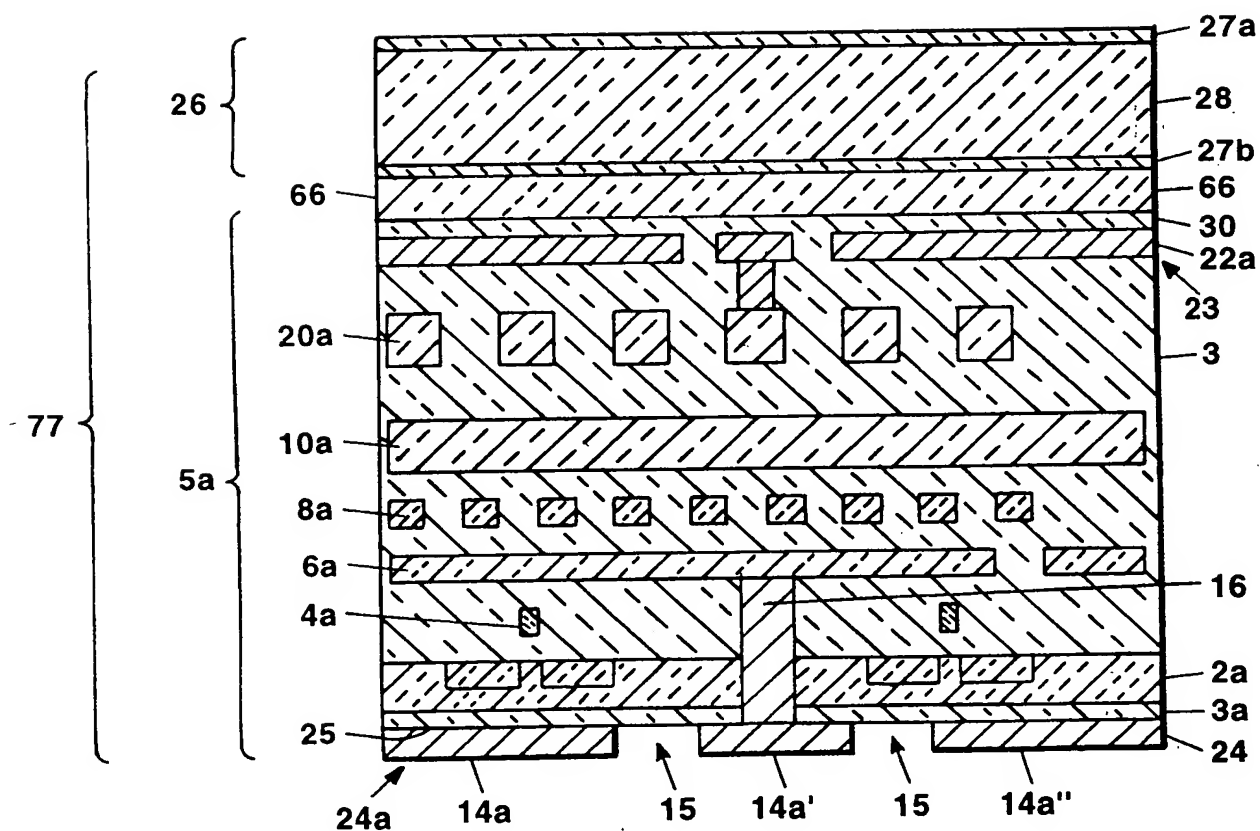


Figure 2D



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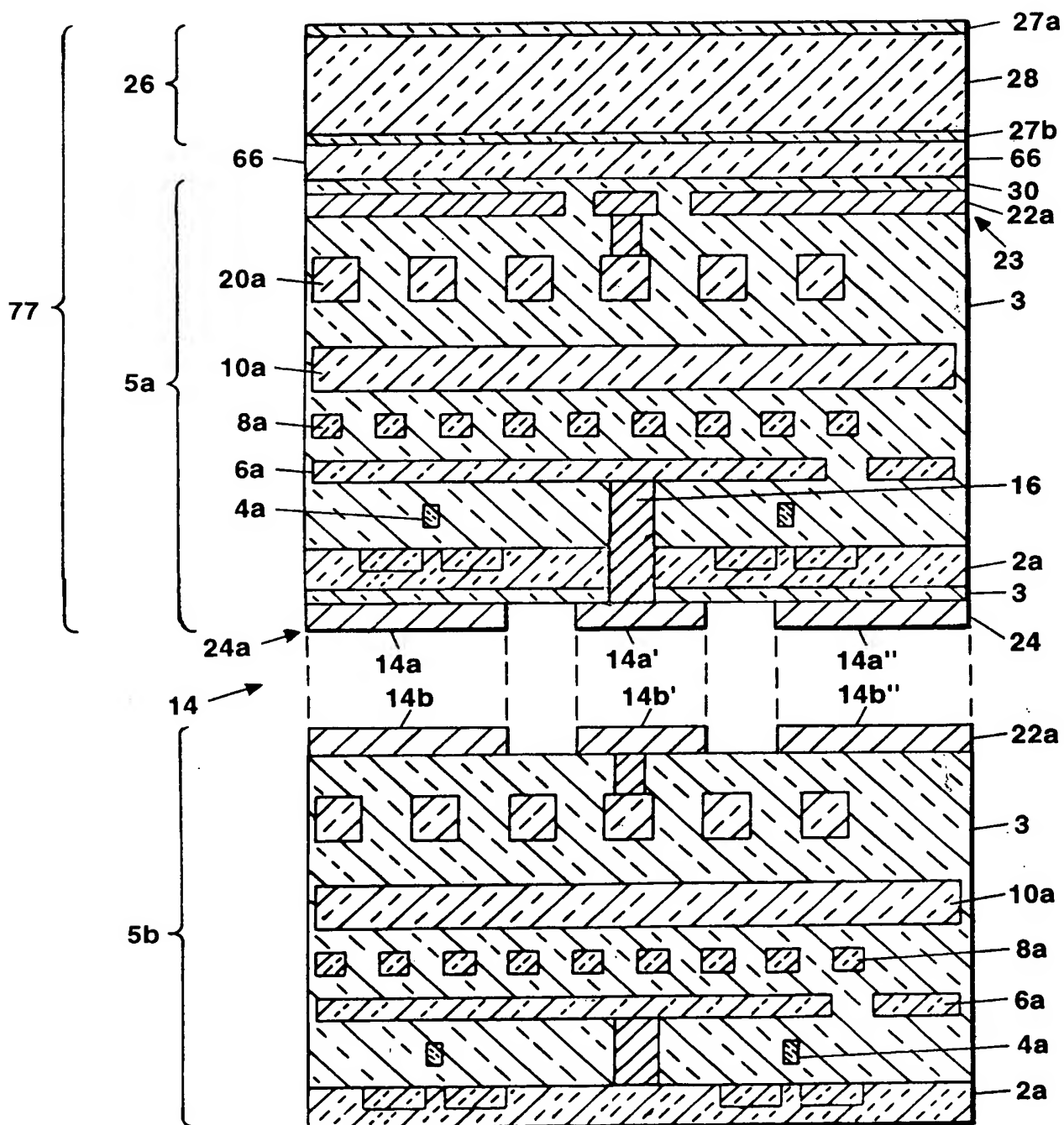


Figure 3A



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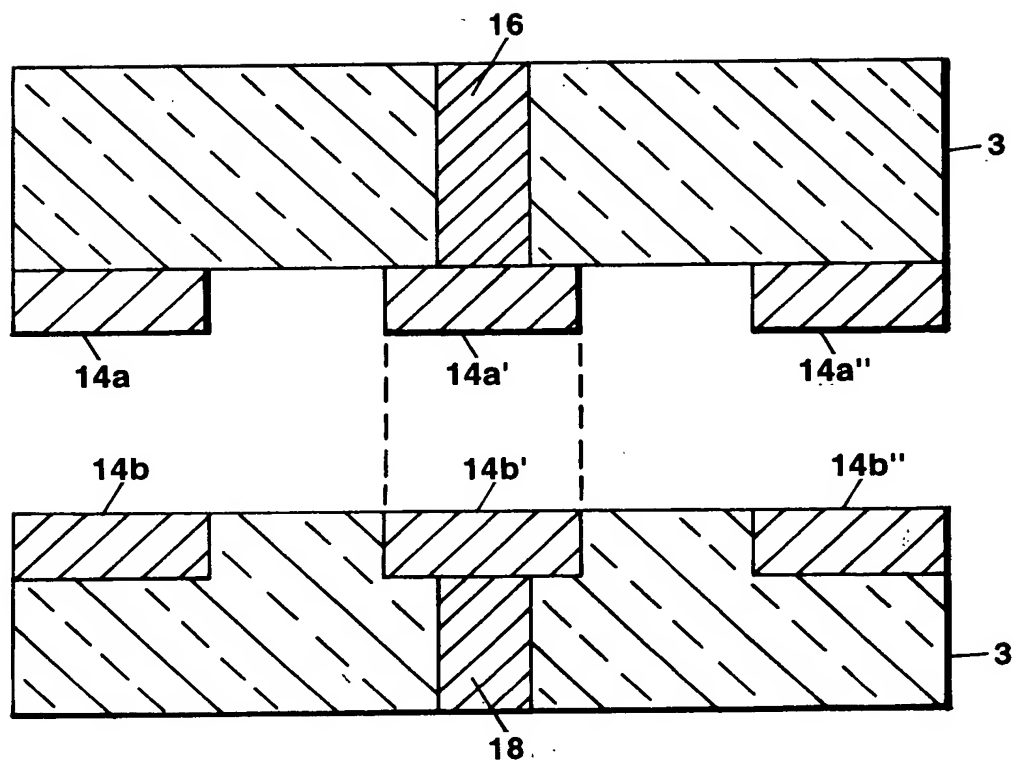


Figure 3B



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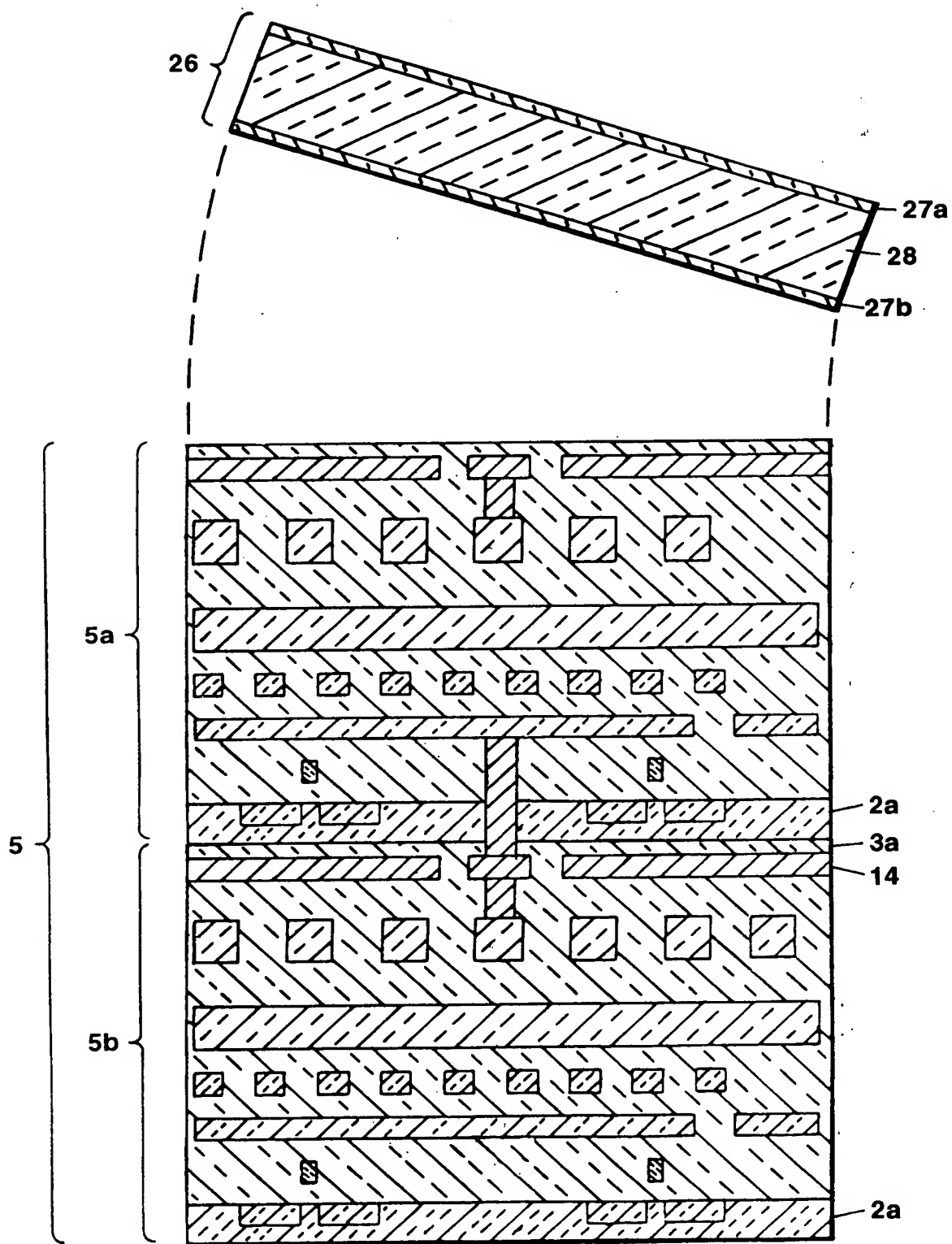


Figure 4A



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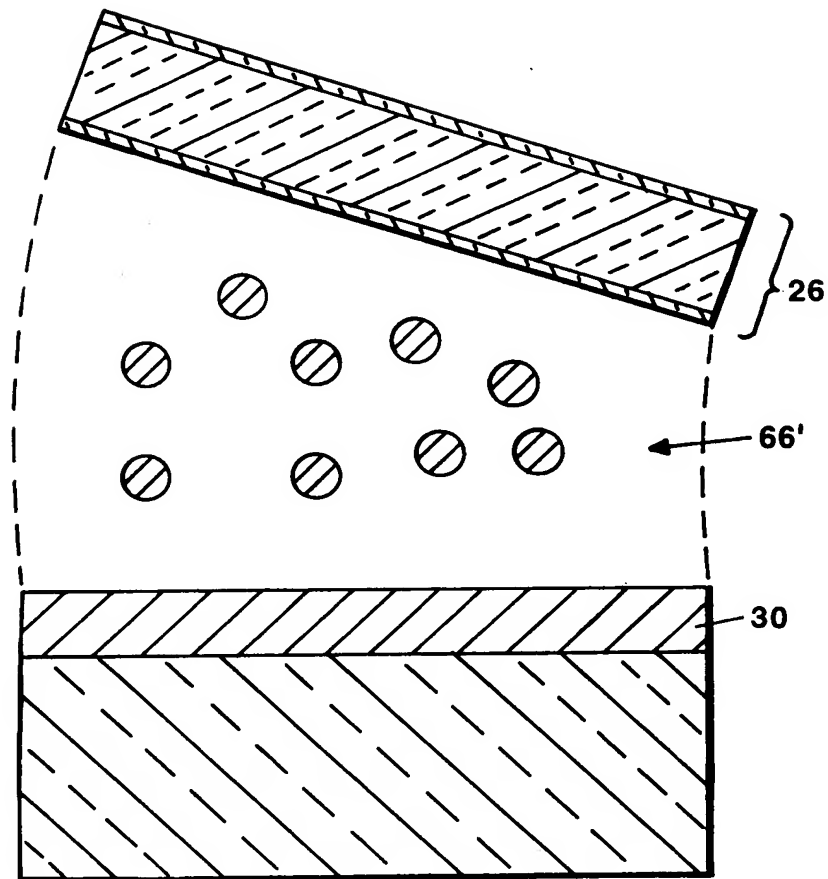


Figure 4B